# NHP260SF, NRVHP260SF

# Surface Mount Ultrafast Power Rectifier

## Plastic SOD−123FL Package

This SOD−123FL ultrafast rectifier provides fast switching performance with soft recovery in a compact thermally efficient package. Its compact footprint makes it ideally suited to portable and automotive applications where board space is at a premium. Its low profile makes it a good option for flat panel display and other applications with limited vertical clearance. The device offers low leakage over temperature making it a good match for applications requiring low quiescent current.

### Features

- Fast Soft Switching for Reduced EMI and Higher Efficiency
- Low Profile − Maximum Height of 1.0 mm
- Small Footprint − Footprint Area of 5.94 $mm^2$
- NRV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q101 Qualified and PPAP Capable
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

### Mechanical Characteristics:

- Case: Molded Epoxy
- Epoxy Meets UL 94 V−0 @ 0.125 in
- Weight: 11.7 mg (Approximately)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Maximum for 10 Seconds
- MSL 1

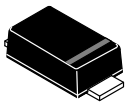
### Applications

- Automotive HID Lighting
- Diesel Piezo Injection
- Power Factor Correction in Mini Adapters
- Freewheeling Diode Where Space is at a Premium

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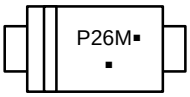
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**ULTRAFAST RECTIFIER**
**2.0 AMPERES**
**600 VOLTS**



**SOD−123FL**
**CASE 498**
**PLASTIC**

**MARKING DIAGRAM**




P26 = Specific Device Code
M = Date Code
▪ = Pb−Free Package
(Note: Microdot may be in either location)

**ORDERING INFORMATION**

| Device | Package | Shipping† |
|---|---|---|
| NHP260SFT3G | SOD−123 (Pb−Free) | 10000/Tape & Reel |
| NRVHP260SFT3G | SOD−123 (Pb−Free) | 10000/Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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## MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|---|---|---|
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage | $V_{RRM}$<br>$V_{RWM}$<br>$V_R$ | 600 | V |
| Average Rectified Forward Current<br>($T_L$ = 130°C) | $I_O$ | 2.0 | A |
| Peak Repetitive Forward Current<br>(Square Wave, 20 kHz, $T_L$ = 115°C) | $I_{FRM}$ | 4.0 | A |
| Non−Repetitive Peak Surge Current<br>(Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz) | $I_{FSM}$ | 15 | A |
| Storage and Operating Junction Temperature Range (Note 1) | $T_{stg}$, $T_J$ | −65 to +175 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The heat generated must be less than the thermal conductivity from Junction−to−Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

## THERMAL CHARACTERISTICS

| Characteristic | Symbol | Value | Unit |
|---|---|---|---|
| Thermal Resistance, Junction−to−Lead (Note 2) | $\Psi_{JCL}$ | 12 | °C/W |
| Thermal Resistance, Junction−to−Ambient (Note 2) | $R_{\theta JA}$ | 86.7 | °C/W |
| Thermal Resistance, Junction−to−Ambient (Note 3) | $R_{\theta JA}$ | 330 | °C/W |

## ELECTRICAL CHARACTERISTICS

| Characteristic | Test Conditions | Symbol | Typ | Max | Unit |
|---|---|---|---|---|---|
| Instantaneous Forward Voltage (Note 4) | ($I_F$ = 2 A, $T_C$ = 125°C)<br>($I_F$ = 2 A, $T_C$ = 25°C) | $V_F$ | 2.1<br>3.3 | 3.0<br>4.2 | V |
| Instantaneous Reverse Current (Note 4) | (Rated DC Voltage, $T_C$ = 125°C)<br>(Rated DC Voltage, $T_C$ = 25°C) | $I_R$ | 5.0<br>0.02 | 50<br>1.0 | μA |
| Reverse Recovery Time<br>Peak Reverse Recovery Current<br>Total Reverse Recovery Charge<br>Softness Factor | ($I_F$ = 2 A, $d_{IF}/d_t$ = 30 A/μs, $T_C$ = 25°C) | $t_{rr}$<br>$I_{RM}$<br>$Q_{rr}$<br>S | 10<br>0.5<br>2.3<br>0.5 | 50<br>3.0<br>10<br>3.0 | ns<br>A<br>nC<br>– |
| Reverse Recovery Time<br>Peak Reverse Recovery Current<br>Total Reverse Recovery Charge<br>Softness Factor | ($I_F$ = 2 A, $d_{IF}/d_t$ = 30 A/μs, $T_C$ = 125°C) | $t_{rr}$<br>$I_{RM}$<br>$Q_{rr}$<br>S | 43<br>0.8<br>15<br>1.8 | –<br>–<br>–<br>– | ns<br>A<br>nC<br>– |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Mounted with 700 $mm^2$ copper pad size (Approximately 1 $in^2$) 1 oz FR4 Board.
3. Mounted with pad size approximately 20 $mm^2$ copper, 1 oz FR4 Board.
4. Pulse Test: Pulse Width ≤ 380 μs, Duty Cycle ≤ 2.0%.

## TYPICAL CHARACTERISTICS

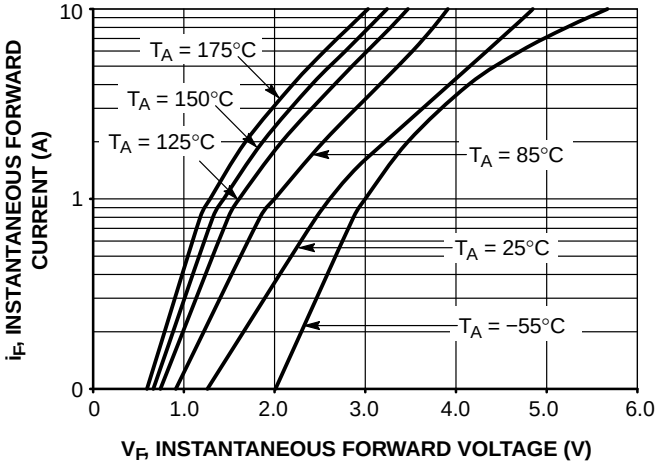



**Figure 1. Typical Instantaneous Forward Characteristics**

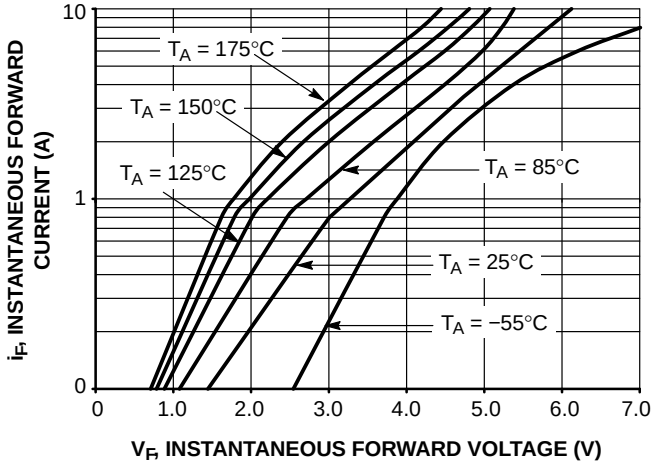



**Figure 2. Maximum Instantaneous Forward Characteristics**

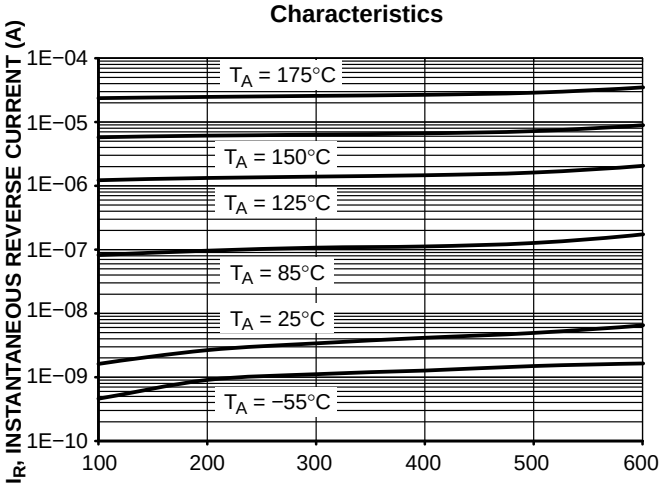



**Figure 3. Typical Reverse Characteristics**

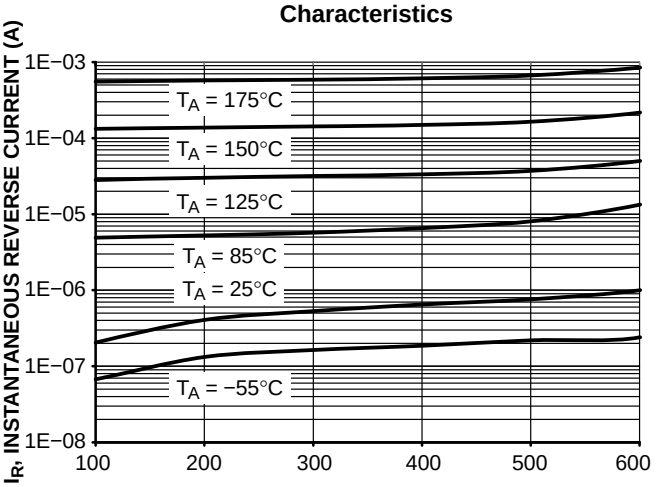



**Figure 4. Maximum Reverse Characteristics**

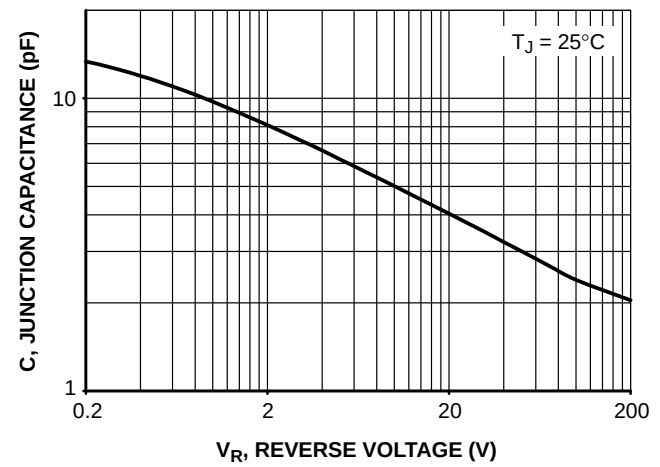



**Figure 5. Typical Junction Capacitance**

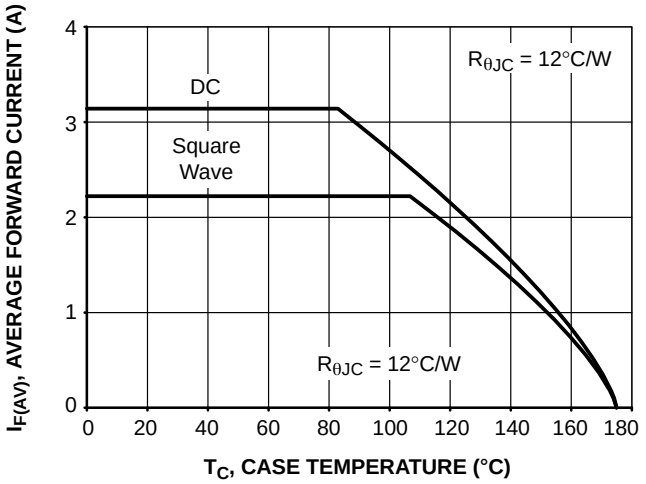



**Figure 6. Current Derating**

## TYPICAL CHARACTERISTICS

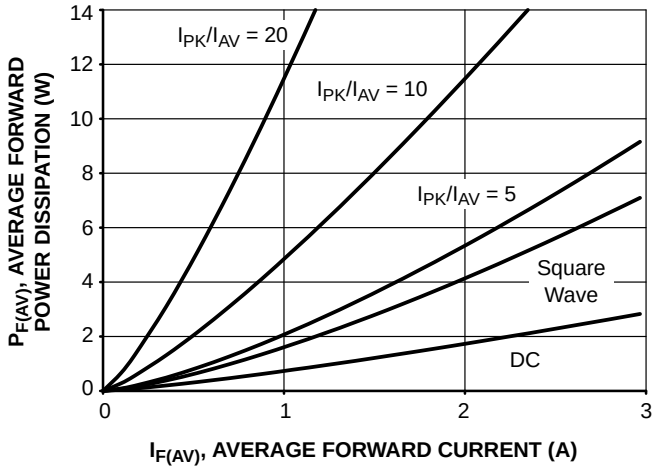



**Figure 7. Forward Power Dissipation**

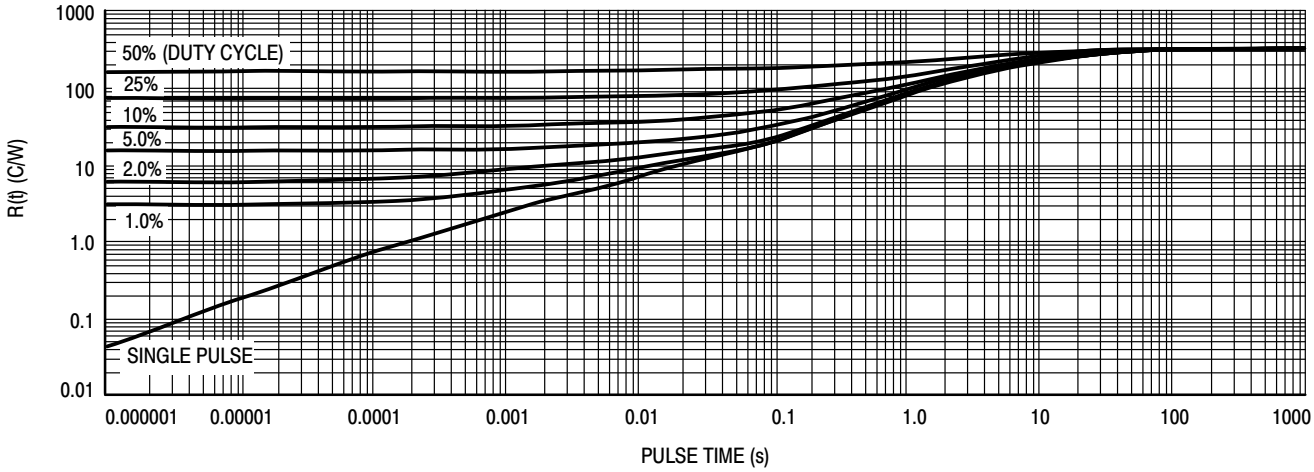



**Figure 8. Thermal Response, Junction−to−Ambient (20 mm$^2$ pad)**

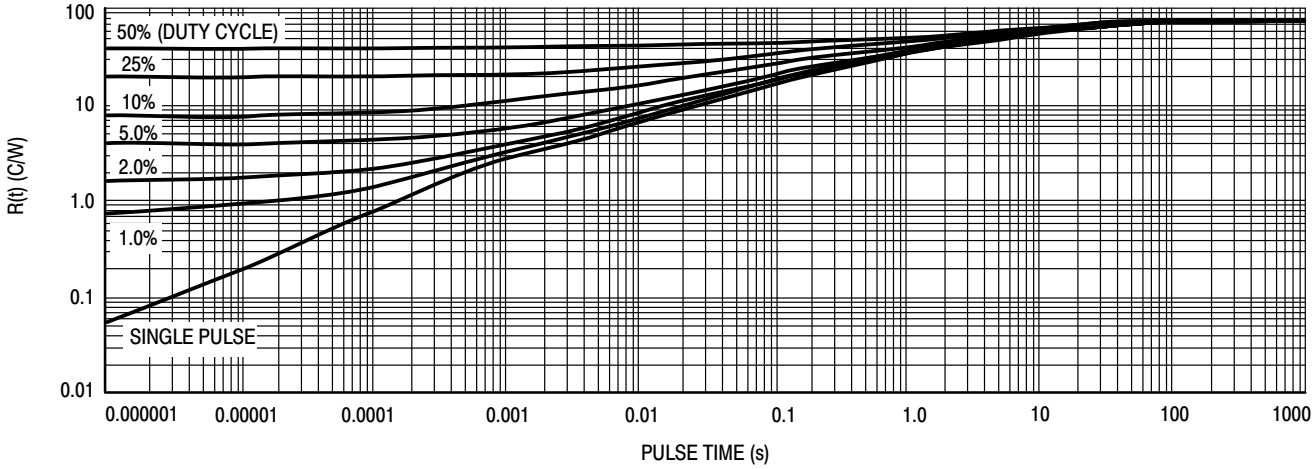
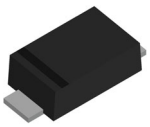


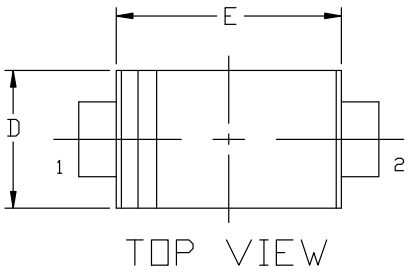

**Figure 9. Thermal Response, Junction−to−Ambient (1 in$^2$ pad)**

# MECHANICAL CASE OUTLINE
## PACKAGE DIMENSIONS

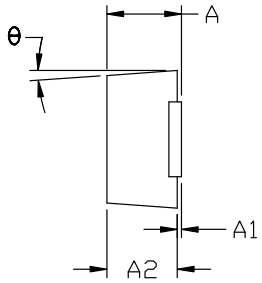


**SOD−123−2 1.65x2.70x0.90**
CASE 498
ISSUE E

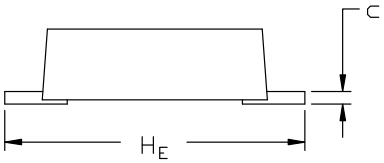
DATE 22 AUG 2023



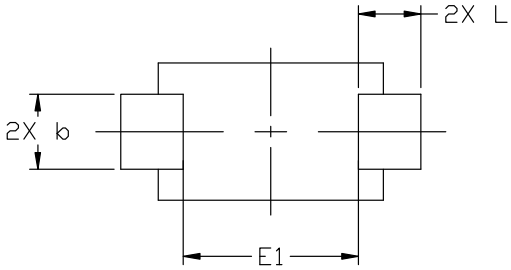

TOP VIEW




END VIEW



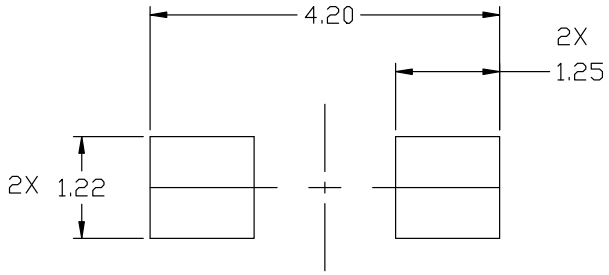

SIDE VIEW




BOTTOM VIEW

| DIM | MILLIMETERS | | |
|---|---|---|---|
| | MIN. | NOM. | MAX. |
| A | 0.90 | 0.95 | 0.98 |
| A1 | 0.00 | 0.05 | 0.10 |
| A2 | 0.85 | 0.90 | 0.95 |
| b | 0.70 | 0.90 | 1.10 |
| c | 0.10 | 0.15 | 0.20 |
| D | 1.50 | 1.65 | 1.80 |
| E | 2.50 | 2.70 | 2.90 |
| E1 | 1.70 | 2.10 | 2.50 |
| $H_E$ | 3.40 | 3.60 | 3.80 |
| L | 0.55 | 0.75 | 0.95 |
| θ | 0° | --- | 8° |

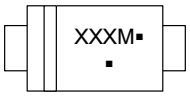
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS b AND L ARE TO BE MEASURED ON A FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 FROM THE LEAD TIP.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH PROTRUSIONS, OR GATE BURRS.
5. FLAT LEAD.




RECOMMENDED
MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**GENERIC MARKING DIAGRAM***




XXX = Specific Device Code
M = Date Code
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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|---|---|---|
| DESCRIPTION: | SOD−123−2 1.65x2.70x0.90 | PAGE 1 OF 1 |

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